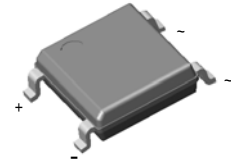
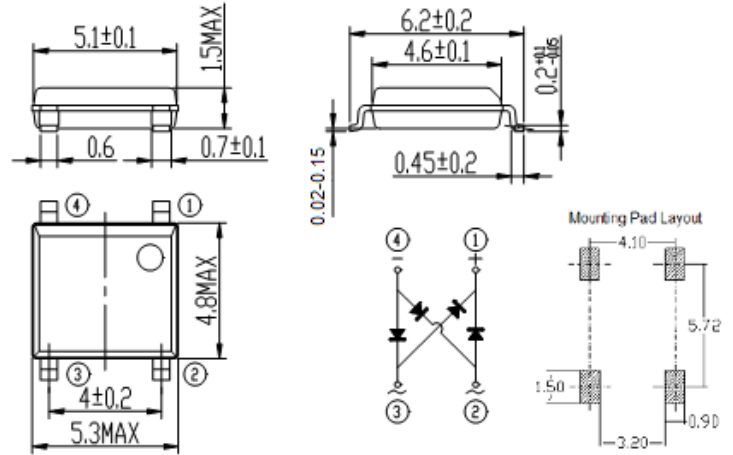


**Features**

Low Profile: Typical height of 1.4mm
Ideal for automated placement
High surge current capability
Solder Dip 260 , 10seconds

**Mechanical Data**

Case:SOPA-4
Epoxy meets UL-94V-0 Flammability rating
Terminals:Matte tin plated leads, solderable per
J-STD-002B and JESD22-B102D
Polarity:As markde on body

**Maximum Ratings & Electrical Characteristics** Ratings at 25

ambient temperature unless otherwise specified.

Parameter	Symbol	LB2SA	LB4SA	LB6SA	LB8SA	LB10SA	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I_{F(AV)}$	0.8 1.0					A
Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	25					A
Rating for fusig (t<8.3ms)	I^2t	2.6					A ² sec
Maximum instantaneous forward voltage drop per diode at 0.4A	V_F	0.95					V
Maximum DC reverse current at $T_A=25$ rated DC blocking voltage per leg $T_A=125$	I_R	5 500					μA
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	80 25					/W
Operating junction temperature range	T_J	-55 to +150					
Storage temperature range	T_{STG}	-55 to +150					

Notes: 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.
2. JEDEC registered values

RATINGS AND CHARACTERISTIC CURVES

($T_A=25^\circ\text{C}$ unless otherwise noted)

